IEEE France Section

IEEE ELECTRONICS PACKAGING SOCIETY
FRANCE chapter

Webinar

IEEE EPS France is pleased to invite you to the webinar given by

John Hunt

Senior Director, Engineering
Marketing & Technical Promotion
ASE (US) Inc

Topic: Fan Out Packaging and its Diversity

Presentation of 40 min duration followed by Q&A

Abstract:

Fan Out technology has evolved in recent years as an alternative package answering a growing need for miniaturization in electronics, while also providing improved electrical interconnectivity for more advanced multi-die solutions. This has been accomplished through the integration of a wide variety of wafer and panel level technologies, processes and materials. Fan out has enabled both the miniaturization of low-end packages for mobile applications, as well as the interconnection required for more advanced complex package assemblies. We will review these Fan Out technologies, including Wafer Level Fanout, Panel Level Fanout, and multiple combinations of chip first and chip last solutions. The resulting packaging combinations that evolve from these technologies will only be limited by our imaginations, and our creativity in innovating them.

Speaker :

John Hunt is Senior Director Engineering, Marketing & Technical Promotion, at ASE (US) Inc., and provides technical support for the Introduction, Engineering, Marketing, and Business Development activities for Advanced Wafer Level and Fan Out Packaging Technologies at ASE.
John has more than 45 years of experience in various areas of manufacturing, assembly and testing of electronic components and systems, with emphasis on the development of new technologies and processes. He has a B.S. from Rutgers and an M.S. from the University of Central Florida.

To register: send an email to jean-charles.souriau@cea.fr

TUESDAY, NOVEMBER 30, 2021
4:30 PM (UTC+01:00) Brussels, Copenhagen, Madrid, Paris